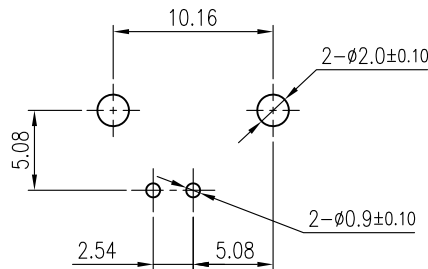
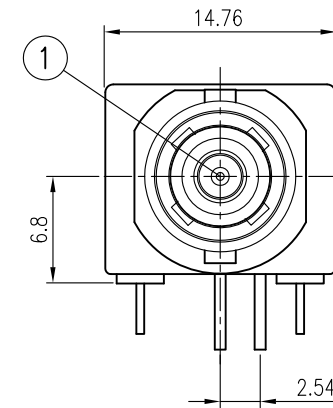
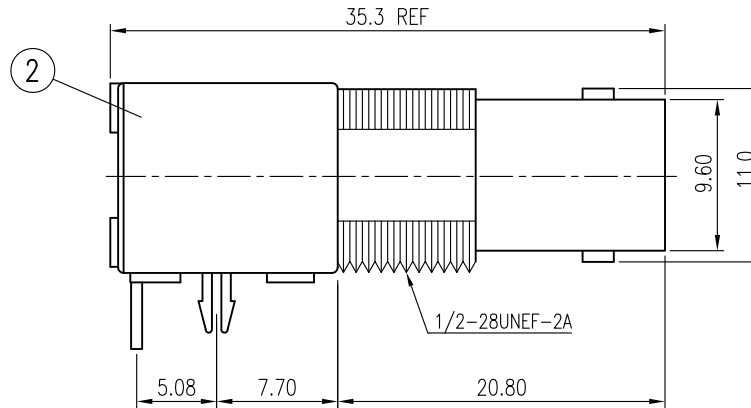
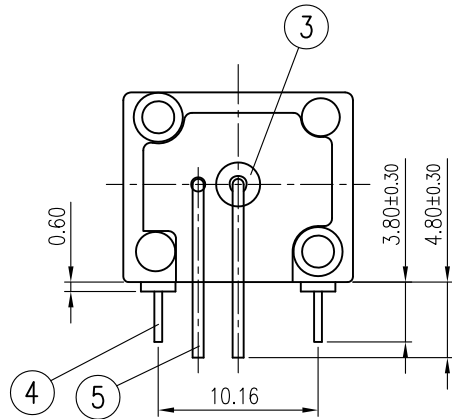


PRELIMINARY RELEASE
SUBJECT TO CHANGE

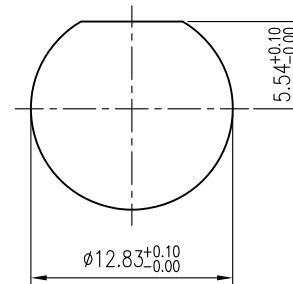
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
AX1		NON-RELEASE REVISION	08/12/2010	Roger Tsai

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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.



RECOMMENDED PC BOARD LAYOUT
WITHOUT MOUNTING POSTS



RECOMMENDED PANEL CUTOUT
MAXIMUM PANEL THICKNESS: 5.5 MM

NOTE: THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2002/95/EC FOR RoHS.

5	SOLDER TAIL	BRASS	NICKEL:0.001μm / TIN:2μm
4	MOUNNT POST	BRASS	NICKEL:0.001μm / TIN:6μm
3	INSULATOR	PE-606	
2	BODY	ZINC ALLOY	CU:12μm / NICKEL:3μm
1	CENTER CONTACT	PHOSPHOR BRONZE	NICKEL:6μm / AU:0.001μm
REF.	DESCRIPTION	MATERIAL	PLATING

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol®		
X.		DRAWN Roger Tsai		08/12/2010	BNC R/A PCB MOUNT JACK, METAL BODY, 75 OHMS		Amphenol Corporation Amphenol Taiwan Corporation		
X.X	±0.30	CHECKED Aqua Chou		08/12/2010					
X.XX	±0.20	APPROVED Roger Tsai		08/12/2010					
X.XXX	±0.10	DWG TYPE CUST DWG		PROJECT CODE RFM	UNIT mm	SIZE A3	PART No.	G11A0375EU	
ANGULAR	±1°	UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 1 OF 1	DWG No.	G11A0375EU	REV. AX1